

1. Soldering

(1) Re-flow soldering

Please mount component on a circuit board by re-flow soldering. Flow soldering is not acceptable.

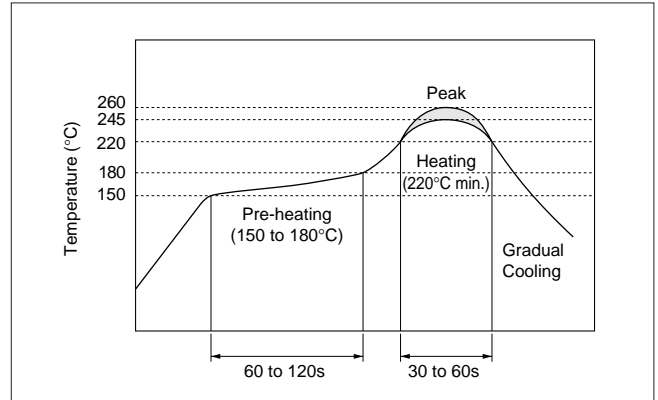
Recommendable Flux and Solder

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|--------|---|
| Flux | Please use rosin based flux, but do not use water soluble flux. |
| Solder | Please use solder (Sn-3.0Ag-0.5Cu) under the following condition. Standard thickness of soldering paste: 0.10 to 0.15mm |

Recommendable Soldering Profile

| | | |
|------------------|--------------------|------------|
| Pre-heating | 150 to 180°C | 60 to 120s |
| Heating | 220°C min. | 30 to 60s |
| Peak Temperature | upper limit: 260°C | 1s max. |
| | lower limit: 245°C | 5s max. |

Temperature shall be measured on the surface of component.



(2) Soldering with iron

Be compelled to mount component by using soldering iron, please do not directly touch the component with soldering iron. The terminals of component or electrical characteristics may be damaged if excess thermal stress is applied.

Recommendable Soldering with Iron

| | |
|-------------------------------|-------------------------|
| Heating of the soldering iron | 350°C max. |
| Watt | 30W max. |
| Shape of the soldering iron | ø3mm max. |
| Soldering Time | 5s max. at one terminal |
| Solder | Sn-3.0Ag-0.5Cu |

(3) etc.

Do not reuse removed component from a circuit board after soldering.

(4) Condition for Placement machines

The component is recommended with placement machines with employ optical placement capabilities. The component might be resulted in damage by excessive mechanical force. Please make sure that you have evaluated by using placement machines before going into mass production. Do not use placement machines which utilize mechanical positioning. Please contact Murata for details beforehand.

2. Washing / Coating

Conformal coating or washing to the component is not acceptable, because it is not hermetically sealed.

Please contact us in case you need washable component.